

## EAST Search History

## EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	574	333/186	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:35
L3	241	333/197	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:35
L6	148	333/200	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:45
L7	81	257/E23.181	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:46
L8	2367	438/125	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:47
L9	1865	438/126	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 19:50
S1	5	"5,477,008".pn. or "20040065932" or "20040028849"	US-PGPUB; USPAT	OR	OFF	2008/06/09 07:08

S2	20	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or hermetica\$3)	USPAT	OR	ON	2008/06/09 07:10
S3	18	("4838088"   "5188983"   "5589082"   "5631428"   "5668033"   "5783749"   "5937275"   "5952572"   "6133146"   "6140144"   "6232150"   "6265246"   "6297072"   "6335224"   "6635509").PN. OR ("6902656").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S4	7	("5025346"   "5028983"   "5454158"   "5523619"   "5686697"   "5822856"   "6178093").PN. OR ("6779247").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S5	40	("5589082"   "5668033"   "5783749"   "5937275"   "5952572"   "6140144"   "6232150"   "6265246"   "6297072"   "6335224").PN. OR ("6635509").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:15
S7	6	("5589082"   "5963788"   "6174820"   "6429755"   "6628177"   "6635509").PN. OR ("7002436").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:23
S8	68	("4918032"   "4997521").PN. OR ("5589082").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:31

S11	194	"20010001931"   "20010009110"   "20010034076"   "20020016058"   "20020135047"   "20040016989"   "20040065932"   "4665610"   "4674319"   "4766666"   "4849071"   "4945769"   "4990462"   "5075253"   "5139624"   "5156903"   "5338416"   "5445991"   "5455547"   "5461916"   "5470797"   "5491604"   "5504026"   "5510156"   "5517123"   "5537083"   "5540095"   "5583290"   "5589082"   "5604312"   "5613611"   "5616514"   "5620931"   "5627317"   "5627318"   "5631422"   "5640039"   "5679436"   "5683591"   "5703293"   "5721377"   "5723353"   "5728936"   "5751041"   "5760455"   "5761957"   "5804083"   "5818227"   "5839062"   "5847280"   "5858809"   "5872024"   "5880369"   "5889207"   "5898218"   "5919364"   "5922212"   "5937275"   "5948991"   "5955932"   "5959208"   "5969249"   "5986316"   "5987989"   "5992233"   "6009753"   "6028332"   "6035714"   "6048774"   "6055858"   "6065341"   "6067858"   "6090718"   "6100108"   "6106735"   "6117701"   "6119518"   "6122964"   "6125700"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/06/09 07:41
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S13	67	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:56
S14	1497	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:58
S15	1599	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 07:59
S16	1033	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:11

S17	424	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:28
S18	672	polysilicon with polymer	USPAT	OR	OFF	2008/06/09 08:34
S19	4	polysilicon with polymerized near material	USPAT	OR	OFF	2008/06/09 08:34
S20	27	polysilicon with polymerized	USPAT	OR	OFF	2008/06/09 08:35
S21	3437	polysilicon with glass	USPAT	OR	OFF	2008/06/09 08:38
S22	937	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:41
S23	315	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 08:49
S24	288	polysilicon near glass	USPAT	OR	OFF	2008/06/09 08:49
S25	5685	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:01
S26	301	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:25
S27	0	porous near silicon with photoresis	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:40

S28	72	porous near silicon with photoresist	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:40
S29	2112	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:50
S30	1095	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:53
S31	0	photoresists with plug same micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:54
S32	0	photoresists with plug and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:54
S33	0	photoresists with (plug or cover) and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:55
S34	0	photoresists same (plug or cover) and micro near component	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 09:55
S35	4008	photoresist with (silicon near dioxide or alumina)	USPAT	OR	OFF	2008/06/09 09:59
S36	326	photoresist near material with (silicon near dioxide or alumina)	USPAT	OR	OFF	2008/06/09 09:59

S37	1196	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/06/09 10:17
S38	798	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with polyimide	USPAT	OR	ON	2008/12/29 22:30
S39	32	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with polyimide and mems	USPAT	OR	ON	2008/12/29 22:30
S40	119	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:33
S41	6051	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:33
S42	1614	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:34
S43	4	(semiconductor or die or dice or chip or IC) and (cavity or open\$3 or recess or aperture) with cover\$3 and cover \$3 with (fill\$3 or seal \$3) with polyimide and mems	USPAT	OR	ON	2008/12/29 22:36
S44	1727	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/29 22:46



S45	1076	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 13:23
S46	322	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 13:50
S47	870	polysilicon with polymer	USPAT	OR	ON	2008/12/30 13:55
S48	28	polysilicon with made with polymer	USPAT	OR	ON	2008/12/30 13:55
S49	968	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:08
S50	440	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:12
S51	14	polysilicon with part with polymer	USPAT	OR	ON	2008/12/30 14:13
S52	315	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 14:47
S53	13	(semiconductor or die or dice or chip or IC) and micro near cavity with MEMS	USPAT	OR	ON	2008/12/30 14:51
S54	2312	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:17

S55	1188	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 15:26
S56	92	polymer near polysilicon	USPAT	OR	ON	2008/12/30 16:07
S57	1293	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/12/30 16:14
S58	150	257/e29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:24
S59	6294	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:26
S60	1715	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:28
S61	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or cover \$3) and plug with (seal \$3 or cover\$3) and hermetica\$3	USPAT	OR	OFF	2009/05/05 21:31
S62	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or cover \$3) and plug with (seal \$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:31

S63	4	(semiconductor or die or dice or chip or IC) and micro near cavity with (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:31
S64	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrificial) same (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:33
S65	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrificial) and (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:33
S66	0	(semiconductor or die or dice or chip or IC) and micro near cavity with (sacrific\$3) and (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:33
S67	4	(semiconductor or die or dice or chip or IC) and micro near cavity and (sacrific\$3) and (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:33

S68	11	("20040053434"   "20040065932"   "20040126953"   "5329110"   "5597957"   "6274440"   "6582569"   "6590280"   "6636002"   "6787387"   "6924485").PN. OR ("7364932").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:37
S69	23	("4115719"   "4147929"   "4148050"   "4534099"   "4557037"   "4758734"   "4826777"   "4925805"   "4990827"   "5098856"   "5264693").PN. OR ("5329110").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:42
S70	14	("2867729"   "3310701"   "3435233"   "3475076"   "3873829"   "3896305").PN. OR ("4147929").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:44
S71	1810	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:46
S72	258	(semiconductor or die or dice or chip or IC) and cavity and (sacrific \$3) and (seal\$3 or cover\$3) and (open\$3 or via or aperture or window) with (seal\$3 or cover\$3) and hermetica\$3	USPAT	OR	ON	2009/05/05 21:46

S73	19	("20020075094"   "20020171517"   "20030047533"   "20030155643"   "20040173886"   "20050074919"   "5090254"   "5589082"   "6118164"   "6133807"   "6444135"   "6452124"   "6452238"   "6472739"   "6621387"   "6635509"   "6673697"   "6686820"   "7102472").PN. OR ("7381583").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:50
S74	1102	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 21:54
S75	75	("4918032"   "4997521").PN. OR ("5589082").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/05 21:55
S76	326	257/420	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:00
S77	999	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:09
S78	445	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:10
S79	324	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:12

S80	2438	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:16
S81	1252	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:19
S82	1355	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/05/05 22:28
S83	43	("20040219706"   "4990229"   "5242863"   "5397962"   "5448068"   "5486491"   "5493177"   "5550090"   "5593495"   "5640042"   "5694134"   "5801383"   "5886867"   "5891751"   "5921461"   "5929497"   "5990766"   "6060336"   "6074971"   "6093579"   "6117787"   "6135856"   "6258223"   "6262417"   "6284149"   "6294425"   "6377142"   "6377217"   "6377440"   "6404614"   "6440289"   "6492883"   "6514895"   "6525630"   "6534850"   "6535076"   "6543292"   "6547973"   "6556102"   "6570750"   "6590468"   "6593242"   "6597265").PN. OR ("7429495").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2009/05/12 17:25
S84	134	photoresists with silicon near nitride	USPAT	OR	OFF	2009/05/12 19:47

S85	0	photoresists near material with silicon near nitride	USPAT	OR	OFF	2009/05/12 19:50
S86	351	photoresists near material with silicon near nitride	USPAT	OR	ON	2009/05/12 19:50
S87	1280	photoresists near material with silicon	USPAT	OR	ON	2009/05/12 19:53
S88	136	photoresists near material near silicon	USPAT	OR	ON	2009/05/12 19:53
S89	29	plug with phosphosilicate near glass	USPAT	OR	ON	2009/05/12 20:36
S90	0	plug near phosphosilicate near glass	USPAT	OR	ON	2009/05/12 20:38
S91	86	plug with (phosphosilicate near glass or "PSG")	USPAT	OR	ON	2009/05/12 20:40
S92	57	S91 not S89	USPAT	OR	ON	2009/05/12 20:40
S93	0	plug near (phosphosilicate near glass or "PSG")	USPAT	OR	ON	2009/05/12 20:41
S94	0	seal\$3 with (hole or via or open\$3) with phosphosilicate near glass	USPAT	OR	ON	2009/05/12 20:43
S95	5	seal\$3 with (hole or via or open\$3) and seal\$3 with phosphosilicate near glass	USPAT	OR	ON	2009/05/12 20:44
S96	203	257/E29.324	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 13:47
S97	6559	257/678	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 13:47

S98	345	257/619	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 13:48
S99	1820	257/414	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 14:17
S100	1934	257/415	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 14:18
S101	1136	257/417	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 14:26
S102	450	257/418	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 14:49
S103	1054	257/419	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 16:32
S104	2611	438/48	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 16:34
S105	1331	438/50	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 16:58



S106	1421	438/52	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/09 17:25
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**10/ 9/ 09 7:54:02 PM**

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